

#### Is Now Part of



## ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at <a href="https://www.onsemi.com">www.onsemi.com</a>

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo



September 1983 Revised May 2005

## MM74HC245A Octal 3-STATE Transceiver

#### **General Description**

The MM74HC245A 3-STATE bidirectional buffer utilizes advanced silicon-gate CMOS technology, and is intended for two-way asynchronous communication between data buses. It has high drive current outputs which enable high speed operation even when driving large bus capacitances. This circuit possesses the low power consumption and high noise immunity usually associated with CMOS circuitry, yet has speeds comparable to low power Schottky TTL circuits.

This device has an active LOW enable input  $\overline{G}$  and a direction control input, DIR. When DIR is HIGH, data flows from the A inputs to the B outputs. When DIR is LOW, data flows from the B inputs to the A outputs. The MM74HC245A transfers true data from one bus to the other.

This device can drive up to 15 LS-TTL Loads, and does not have Schmitt trigger inputs. All inputs are protected from damage due to static discharge by diodes to  $V_{CC}$  and ground.

#### **Features**

- Typical propagation delay: 13 ns
- Wide power supply range: 2-6V
- Low quiescent current: 80 µA maximum (74 HC)
- 3-STATE outputs for connection to bus oriented systems
- High output drive: 6 mA (minimum)
- Same as the 645

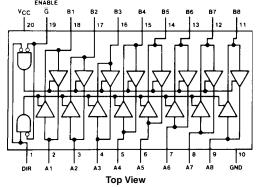
#### **Ordering Code:**

Order Number	Package Number	Package Description
MM74HC245AWM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HC245ASJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC245AMTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC245AN	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

#### **Connection Diagram**

#### Pin Assignments for DIP, SOIC, SOP and TSSOP



#### **Truth Table**

	Control Inputs G DIR		Operation
	L	L	B data to A bus
	L	Н	A data to B bus
	Η	Х	Isolation

- H = HIGH Level
- L = LOW Level X = Irrelevant

### **Absolute Maximum Ratings**(Note 1)

(Note 2)

Supply Voltage (V <sub>CC</sub> )	-0.5 to +7.0V
DC Input Voltage DIR and $\overline{G}$ pins (V <sub>IN</sub> )	-1.5 to V <sub>CC</sub> +1.5V
DC Input/Output Voltage (V <sub>IN</sub> , V <sub>OUT</sub> )	$-0.5$ to $V_{CC}$ +0.5V
Clamp Diode Current (I <sub>CD</sub> )	±20 mA
DC Output Current, per pin (I <sub>OUT</sub> )	±35 mA
DC $V_{CC}$ or GND Current, per pin ( $I_{CC}$ )	±70 mA
Storage Temperature Range (T <sub>STG</sub> )	-65°C to +150°C
Power Dissipation (P <sub>D</sub> )	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T <sub>L</sub> )	
(Soldering 10 seconds)	260°C

## Recommended Operating Conditions

	Min	Max	Units		
Supply Voltage (V <sub>CC</sub> )	2	6	V		
DC Input or Output Voltage					
$(V_{IN}, V_{OUT})$	0	$V_{CC}$	V		
Operating Temperature Range (T <sub>A</sub> )	-40	+85	°C		
Input Rise/Fall Times					
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns		
V <sub>CC</sub> = 4.5V		500	ns		
$V_{CC} = 6.0V$		400	ns		
Note 1: Maximum Ratings are those values beyond which damage to the					

device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: – 12 mW/°C from 65°C to 85°C.

#### DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V <sub>CC</sub>	$T_A = 25$ °C		T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	Units
Symbol	raiametei		*cc	Тур	Guaranteed Limits			Units
V <sub>IH</sub>	Minimum HIGH Level Input		2.0V		1.5	1.5	1.5	V
	Voltage		4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V <sub>IL</sub>	Maximum LOW Level Input		2.0V		0.5	0.5	0.5	V
	Voltage		4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V <sub>OH</sub>	Minimum HIGH Level Output	$V_{IN} = V_{IH}$ or $V_{IL}$						
	Voltage	$ I_{OUT}  \le 20 \ \mu A$	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		$V_{IN} = V_{IH}$ or $V_{IL}$						
		$ I_{OUT}  \le 6.0 \text{ mA}$	4.5V	4.2	3.98	3.84	3.7	V
		$ I_{OUT}  \le 7.8 \text{ mA}$	6.0V	5.7	5.48	5.34	5.2	V
V <sub>OL</sub>	Maximum LOW Level Output	$V_{IN} = V_{IH}$ or $V_{IL}$						
	Voltage	$ I_{OUT}  \le 20 \ \mu A$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ or $V_{IL}$						
		$ I_{OUT}  \le 6.0 \text{ mA}$	4.5V	0.2	0.26	0.33	0.4	V
		$ I_{OUT}  \le 7.8 \text{ mA}$	6.0V	0.2	0.26	0.33	0.4	V
I <sub>IN</sub>	Input Leakage	V <sub>IN</sub> = V <sub>CC</sub> to GND	6.0V		±0.1	±1.0	±1.0	μА
	Current (G and DIR)							
l <sub>OZ</sub>	Maximum 3-STATE Output	V <sub>OUT</sub> = V <sub>CC</sub> or GND	6.0V		±0.5	±5.0	±10	μА
	Leakage Current	Enable $\overline{G} = V_{IH}$						
I <sub>CC</sub>	Maximum Quiescent Supply	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0V		8.0	80	160	μΑ
	Current	$I_{OUT} = 0 \mu A$						

Note 4: For a power supply of 5V  $\pm$ 10% the worst case output voltages (V<sub>OH</sub>, and V<sub>OL</sub>) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V<sub>IH</sub> and V<sub>IL</sub> occur at V<sub>CC</sub> = 5.5V and 4.5V respectively. (The V<sub>IH</sub> value at 5.5V is 3.85V.) The worst case leakage current (I<sub>IN</sub>, I<sub>CC</sub>, and I<sub>O2</sub>) occur for CMOS at the higher voltage and so the 6.0V values should be used.

#### **AC Electrical Characteristics**

 $V_{CC} = 5V, T_A = 25^{\circ}C, t_r = t_f = 6ns$ 

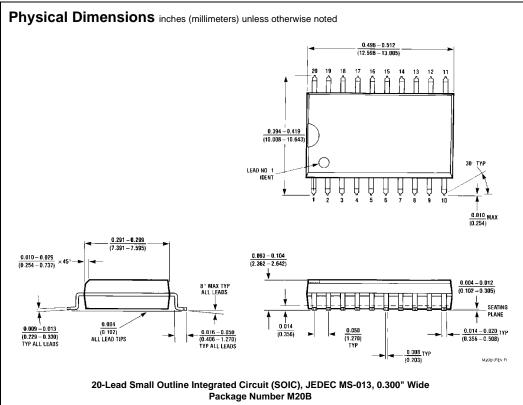
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay	C <sub>L</sub> = 45 pF	12	17	ns
t <sub>PZH</sub> , t <sub>PZL</sub>	Maximum Output Enable	$R_L = 1 k\Omega$	24	35	ns
	Time	C <sub>L</sub> = 45 pF			
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Maximum Output Disable	$R_L = 1 k\Omega$	18	25	ns
	Time	$C_1 = 5 pF$			

#### **AC Electrical Characteristics**

 $\mbox{V}_{CC}$  = 2.0V to 6.0V,  $\mbox{C}_{L}$  = 50 pF,  $\mbox{t}_{r}$  =  $\mbox{t}_{f}$  = 6ns (unless otherwise specified)

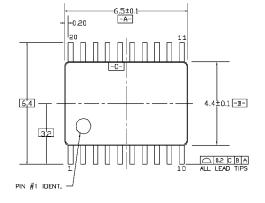
Symbol	Parameter	Conditions	V <sub>CC</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	Units
Symbol			*CC	Тур		Guaranteed L	imits	Units
t <sub>PHL</sub> ,	Maximum Propagation	C <sub>L</sub> = 50 pF	2.0V	31	90	113	135	ns
t <sub>PLH</sub>	Delay	$C_{L} = 150 \text{ pF}$	2.0V	41	96	116	128	ns
		C <sub>L</sub> = 50 pF	4.5V	13	18	23	27	ns
		C <sub>L</sub> = 150 pF	4.5V	17	22	28	33	ns
		C <sub>L</sub> = 50 pF	6.0V	11	15	19	23	ns
		$C_L = 150 pF$	6.0V	14	19	23	28	ns
t <sub>PZH</sub> ,	Maximum Output Enable	$R_L = 1 k\Omega$						
t <sub>PZL</sub>	Time	C <sub>L</sub> = 50 pF	2.0V	71	190	240	285	ns
		C <sub>L</sub> = 150 pF	2.0V	81	240	300	360	ns
		C <sub>L</sub> = 50 pF	4.5V	26	38	48	57	ns
		C <sub>L</sub> = 150 pF	4.5V	31	48	60	72	ns
		C <sub>L</sub> = 50 pF	6.0V	21	32	41	48	ns
		C <sub>L</sub> = 150 pF	6.0V	25	41	51	61	ns
t <sub>PHZ</sub> ,	Maximum Output Disable	$R_L = 1 k\Omega$	2.0V	39	135	169	203	ns
t <sub>PLZ</sub>	Time	$C_L = 50 \text{ pF}$	4.5V	20	27	34	41	ns
			6.0V	18	23	29	34	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Output Rise and Fall Time	C <sub>L</sub> =50 pF	2.0V	20	60	75	90	ns
			4.5V	6	12	15	18	ns
			6.0V	5	10	13	15	ns
C <sub>PD</sub>	Power Dissipation	$\overline{G} = V_{IL}$		50				pF
	Capacitance (Note 5)	$\overline{G} = V_{IH}$		5				pF
C <sub>IN</sub>	Maximum Input Capacitance			5	10	10	10	pF
C <sub>IN/OUT</sub>	Maximum Input/Output			15	20	20	20	pF
	Capacitance, A or B							

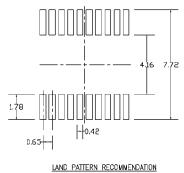
Note 5:  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} \ V_{CC}^2 \ f_{\tau} I_{CC} \ V_{CC}$ , and the no load dynamic current consumption,  $I_g = C_{PD} \ V_{CC} f_{\tau} I_{CC}$ 

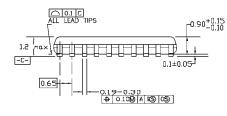


#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 2.6±0.10 0.40 TYP -A-5.01 TYP 5.3±0.10 9.27 TYP 7.8 -B-3.9 ○ 0.2 C B A ALL LEAD TIPS 10 PIN #1 IDENT.-0.6 TYP 1.27 TYP -LAND PATTERN RECOMMENDATION ALL LEAD TIPS SEE DETAIL A 0.1 C 2.1 MAX. 1.8±0.1 0.15±0.05 0.15-0.25 -1.27 TYP 0.35-0.51 **♦** 0.12 **⋈** C A DIMENSIONS ARE IN MILLIMETERS GAGE PLANE 0.25 NOTES: A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998. B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. 0.60±0.15 SEATING PLANE 1.25 -M20DRevB1 DETAIL A 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M20D

#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued)







0.09-0.20

SEE DETAIL A

#### DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MD-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

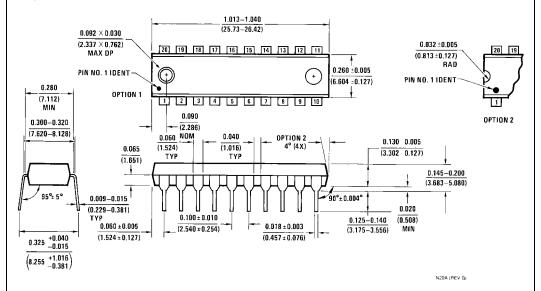
# R0.09min GAGE PLANE - 8-7 -0.6±0.1-0.09min GAGE PLANE R0.09min

DETAIL A

#### MTC20REVD1

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N20A

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdt/Patent-Marking.pdf">www.onsemi.com/site/pdt/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative